

1. Scope :

2. This specification applies to silicon jumpper chips,
Device No. CR-0059

3. Structure :

- 2-1. Silicon substrate
- 2-2. Electrode :
Top-side : Aluminum alloy.
Back side : SnAu Alloy.

4. Size :

- 3-1. *¹Chip size : 57 mils x 62 mils (1.450 mm x 1.600 mm).
 - 3-2. Chip thickness : 9.8 mils $\pm$ 1.0 mil (0.250 mm $\pm$ 0.025 mm)
 - 3-3. Al pad : 48 mils x 54 mils (1.240 mm x 1.390 mm).
 - 3-4. Thickness, frontside metallization: 5 μ m
- ^{*1}Including scribing line (dicing pitch). The chip size is about **(1.415 $\pm$ 0.015)²mm²** after dicing.

5. Visual inspection :

- 4-1. The front side can not be chipped.
- 4-2. The back side chipping or saw damage less than 20% of the chip area.

